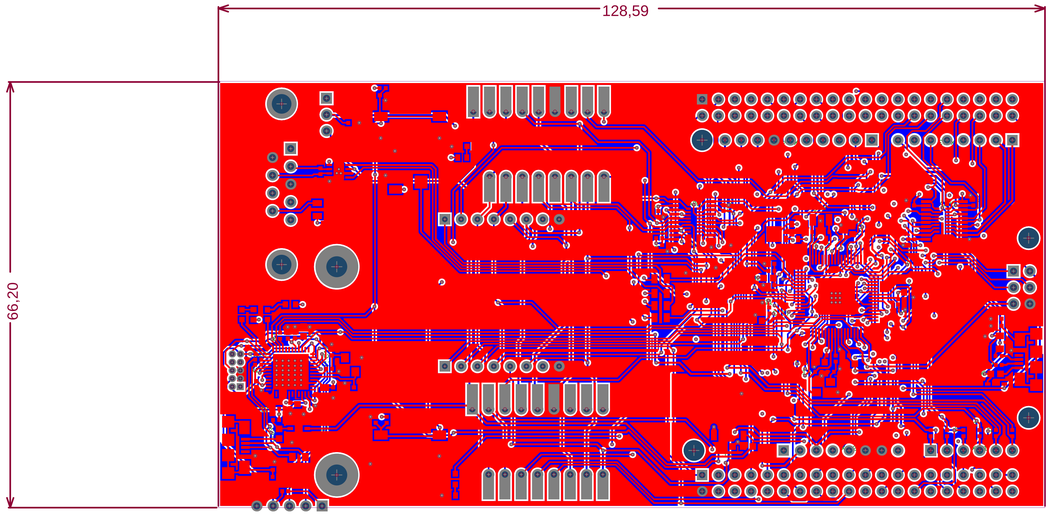

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,79mil	3,5	
1	L1_Top	Copper	2,84mil		
	Dielectric1	FR-4	5,00mil	4,2	
2	Inner 1	Copper	2,84mil		
	Dielectric 3		39,37mil	4,2	
3	Inner 2	Copper	2,84mil		
	Dielectric 2	FR-4	5,00mil	4,2	
4	L2_Bot	Copper	2,84mil		
	Bottom Solder	Solder Resist	0,79mil	3,5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
	2	120,08mil (3,050mm)	PTH	Round	L1_Top - L2_Bot	Pad	Rounded	c460h305m460p460			
	2	128,00mil (3,251mm)	NPTH	Round	L1_Top - L2_Bot	Pad	Rounded	c660hn325m660p660			
	4	125,98mil (3,200mm)	NPTH	Round	L1_Top - L2_Bot	Pad	Rounded	c320hn320			
	9	42,91mil (1,090mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	10	27,95mil (0,710mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	14	43,31mil (1,100mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	16	35,00mil (0,889mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	16	40,16mil (1,020mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	16	43,70mil (1,110mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	34	39,37mil (1,000mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
	80	40,16mil (1,020mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)		3,15mil (0,080mm)	3,15mil (0,080mm)
	411	11,81mil (0,300mm)	PTH	Round	L1_Top - L2_Bot	Via	Rounded	v60h30m0mx0			
	614 Total										

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ENGINEER:		TITLE: Platform2GO XMC4200-V1.1	
PCB DESIGNER: G. Devi			
DATE: 16.03.2020	PART NO.:	REL: R.B.	REV: V1.1
SVN REVISION: 7df790ea8d502e324ae2b6753fcb7675c50b7f9 [Locally Modified]	FILE NAME: Platform2GO XMC4200-V1.1_Layout	APRV: B.	SCALE: 1:1

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